

REMARKS

Entry of Amendment

As Applicants are filing a RCE herewith, this amendment should be entered and considered by the Examiner at this time.

This amendment is in furtherance of Response J filed April 28, 2008 which is incorporated herein by reference.

Amendment To Claims

Applicants are amending independent Claims 1, 36, 48 and 54 to recite the feature of “the planarizing film comprising a resin and having a planarized upper surface so as to reduce a step caused by at least the thin film transistor on a surface of the planarizing film.” This feature is supported by, for example, page 20, lines 9-16 in the specification of the present application. Therefore, no new matter is being added, and it is respectfully requested that this amendment be entered and allowed.

Applicants are also canceling Claims 33, 39, 42-47, 57 and 60-65, without prejudice or disclaimer.

Claim Rejections - 35 USC §103

In the Final Rejection and Advisory Action, the Examiner has the following rejections under 35 U.S.C. §103:

- (a) Claims 1, 3, 32-35 and 48-53 are rejected as being unpatentable over Takahara (U.S. 6,219,113) in view of Tang et al. (U.S. 5,550,066) in further view of Nishiguchi (U.S. 6,046,787).
- (b) Claims 36-41, 54-59 are rejected as being unpatentable over Takahara in view of Tang et al. in view of Hamada (U.S. 6,114,715) and further in view of Nishiguchi.

(c) Claims 42-47 and 60-65 are rejected as being unpatentable over Takahara in view of Tang et al. in view of Zavracky et al. in further view of Hamada, in even further view of Nishiguchi.

Each of these rejections is respectfully traversed.

Applicants' prior response to these rejections in Response J (filed April 28, 2008) is incorporated herein by reference. Applicants will now respond to the specific comments in the Advisory Action.

Previously, in the Final Rejection, the Examiner continued to contend that Tang discloses a planarizing film 52 and cited col. 7, lines 17-19 in Tang in support of this contention. Applicants, however, explained in Response J that Tang merely teaches in column 7, lines 17-19 that "an insulating layer, preferably silicon dioxide, 52 is applied over the entire surface of the device." Hence, Applicants respectfully submitted that Tang does not teach a planarizing film.

In response, in the Advisory Action, the Examiner continues to contend that Tang discloses a planarizing film 52 which meets the claim language. Applicants respectfully disagree.

While Applicants disagree and traverse this rejection, in order to advance the prosecution of this application, Applicants are amending independent Claims 1, 36, 48 and 54 to recite the feature of "the planarizing film comprising a resin and having a planarized upper surface so as to reduce a step caused by at least the thin film transistor on a surface of the planarizing film."

This feature is clearly not disclosed or suggested by Tang or the other cited references. For example, insulating layer 52 in Tang does not have a planarized upper surface that reduces a step caused by the thin film transistor, as the there is a clear step in film 52 over the thin film transistor and no planarized upper surface (layer 52 is also not a resin, as the Examiner admits).

Therefore, independent Claims 1, 36, 48 and 54 are not disclosed or suggested by the cited references, and Claims 1, 36, 48 and 54 and those claims dependent thereon are patentable over the

cited references. Accordingly, it is respectfully requested that the §103 rejections be withdrawn.

Conclusion

It is respectfully submitted that the present application is in a condition for allowance and should be allowed.

If any further fee should be due for this amendment, extension of time, and/or RCE, please charge our deposit account 50/1039.

Favorable reconsideration is earnestly solicited.

Date: June 30, 2008

Respectfully submitted,

/Mark J. Murphy/
Mark J. Murphy
Registration No. 34,225

COOK, ALEX, McFARRON, MANZO,
CUMMINGS & MEHLER, Ltd.
200 West Adams Street, Suite 2850
Chicago, Illinois 60606
(312) 236-8500

Customer No. 26568